

**Average Weight: 10.8689g**

Component	Substance Description	CAS Number or Description	Percentage of Component	Use in Product	Component Weight/ Substance Weight (grams)	Component Percent of Total
<b>Silicon Die</b>					<b>0.694500</b>	<b>6.390</b>
	Silicon	7440-21-3	100.00		0.694500	
<b>Solder Bump</b>					<b>0.036115</b>	<b>0.332</b>
	Tin	7440-31-5	63.00		0.022753	
	Lead	7439-92-1	37.00		0.013363	
<b>Underfill</b>					<b>0.074000</b>	<b>0.681</b>
	Silica	60676-86-0	70.00		0.051800	
	Epoxy Resin A	9003-36-5	20.00		0.014800	
	Epoxy Resin B	25068-38-6	3.00		0.002220	
	Hardener	19900-65-3	7.00		0.005180	
<b>Heat Spreader</b>					<b>6.000000</b>	<b>55.203</b>
	Copper	7440-50-8	99.90		5.994000	
	Nickel	7440-02-0	0.10		0.006000	
<b>Heat Spreader Adhesive</b>					<b>0.130000</b>	<b>1.196</b>
	Organopolysiloxane mixture	NA	100.00		0.130000	
<b>Substrate</b>					<b>2.975310</b>	<b>27.375</b>
	Copper	7440-50-8	47.52	Metal layer	1.390779	
	Nickel	7440-02-0	0.52	Metal layer	0.014877	
	Gold	7440-57-5	0.11	Metal layer	0.003273	
	Glass fiber	NA	10.35		0.309432	
	Halogen fire retardant	NA	5.30		0.156085	
	BT (core)	NA	27.50		0.833087	
	Solder mask	NA	8.70		0.267778	
<b>Solder Balls</b>					<b>0.959000</b>	<b>8.823</b>
	Tin	7440-31-5	63.00		0.60417	
	Lead	7439-92-1	37.00		0.35483	

## Revision History

The following table shows the revision history for this document.

Date	Version	Description of Revisions
3/23/06	1.0	Initial Xilinx release.
7/07/06	1.1	100% Material Declaration.
9/27/06	1.2	Updated component descriptions.
7/20/10	1.3	Updated Heat Spreader substance description.

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